

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A laser submount on top of which a laser is mounted, comprising:

a substrate; ~~and~~

a lens above the substrate and below the laser; and

a top layer on top of which a laser is mounted, the top layer being above the lens.

Claim 2 (original): The laser submount of claim 1, wherein the substrate is selected from the group consisting of silicon, quartz, sodium borosilicate glass, sapphire, gallium arsenide, silicon carbide, and gallium phosphide.

Claim 3 (previously presented): The laser submount of claim 1, further comprising:

a planarization layer covering the lens; and

an interconnect above the planarization layer.

Claim 4 (original): The laser submount of claim 3, wherein the planarization layer is an oxide layer.

Claim 5 (currently amended): The laser submount of claim 3, wherein the top layer comprises a dielectric layer covering the interconnect, the laser submount further comprising:

~~a dielectric layer covering the interconnect; and~~

a contact pad above the dielectric layer, wherein the laser is electrically connected to the contact pad.

Claim 6 (previously presented): The laser submount of claim 5, further comprising:

a sealing ring above the dielectric layer and surrounding the contact pad and the laser.

Claim 7 (original): The laser submount of claim 1, further comprising:

at least one of a passive integrated circuit and an active integrated circuit.

Claims 8 to 14 (canceled).

Claim 15 (previously presented): A laser submount on top of which a laser is mounted, comprising:

a substrate;

a lens above the substrate and below the laser;

a planarization layer covering the lens;

an interconnect above the planarization layer;

a dielectric layer covering the interconnect;

a contact pad above the dielectric layer, wherein the laser is electrically connected to the contact pad; and

~~The laser submount of claim 5, further comprising:~~

a plug electrically connecting the interconnect and the contact pad.

Claim 16 (previously presented): A laser submount on top of which a laser is mounted, comprising:

a substrate;

a lens above the substrate and below the laser;

a planarization layer covering the lens;

an interconnect above the planarization layer;

a dielectric layer covering the interconnect;

a contact pad above the dielectric layer, wherein the laser is electrically connected to the contact pad;

a sealing ring above the dielectric layer and surrounding the contact pad and the laser;

~~The laser submount of claim 6, further comprising:~~

a first plug electrically connecting the interconnect and the contact pad;
another contact pad above the dielectric layer and outside of the seal sealing ring; and
a second plug electrically connecting the interconnect and the another contact pad.